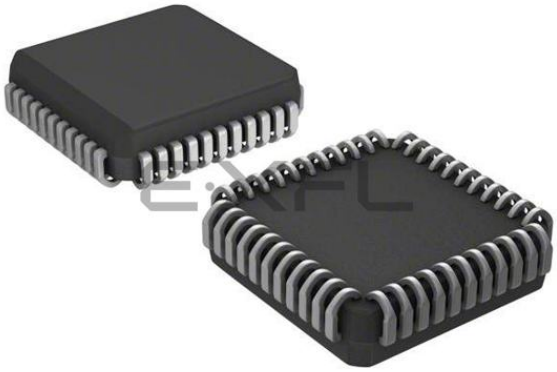


Welcome to E-XFL.COM

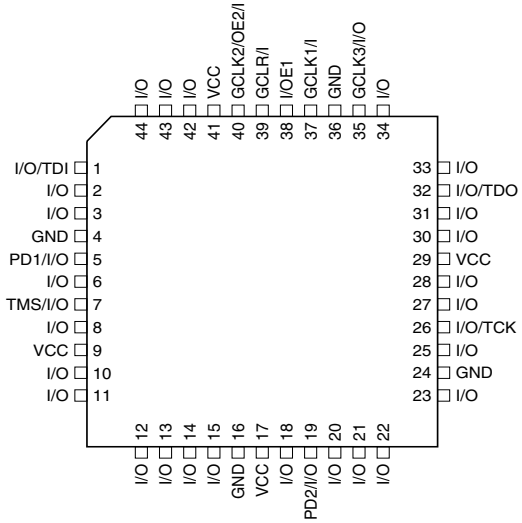
Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

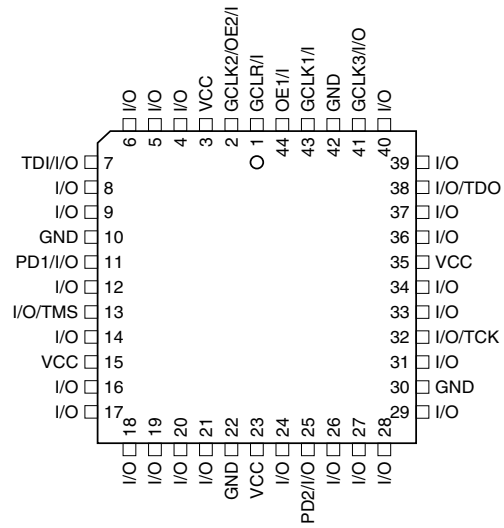
Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable (min 10K program/erase cycles)
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	32
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atf1502as-15ji

44-lead TQFP
Top View



44-lead PLCC
Top View

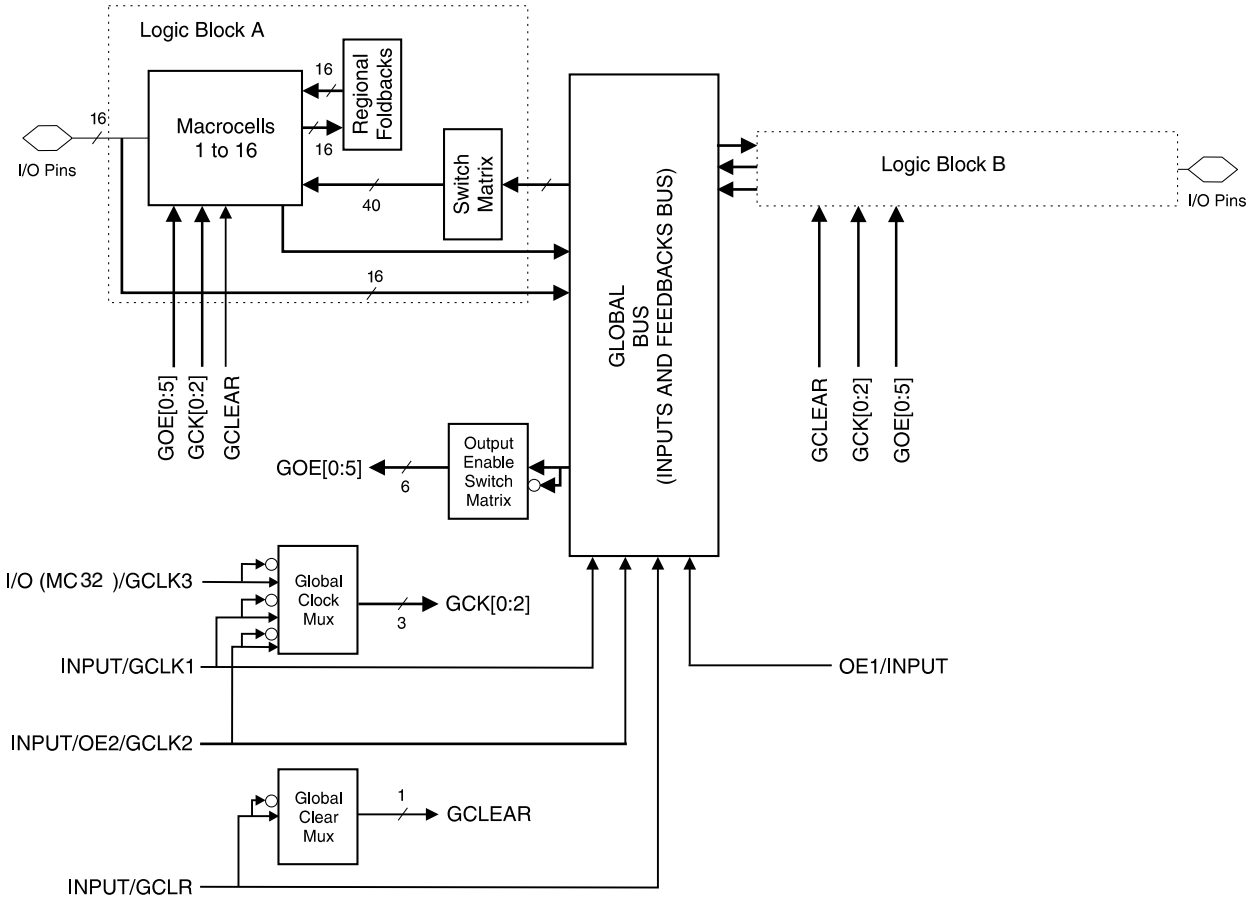


Description

The ATF1502AS is a high-performance, high-density complex programmable logic device (CPLD) that utilizes Atmel's proven electrically-erasable technology. With 32 logic macrocells and up to 36 inputs, it easily integrates logic from several TTL, SSI, MSI, LSI and classic PLDs. The ATF1502AS's enhanced routing switch matrices increase usable gate count and the odds of successful pin-locked design modifications.

The ATF1502AS has up to 32 bi-directional I/O pins and four dedicated input pins, depending on the type of device package selected. Each dedicated pin can also serve as a global control signal, register clock, register reset or output enable. Each of these control signals can be selected for use individually within each macrocell.

Block Diagram



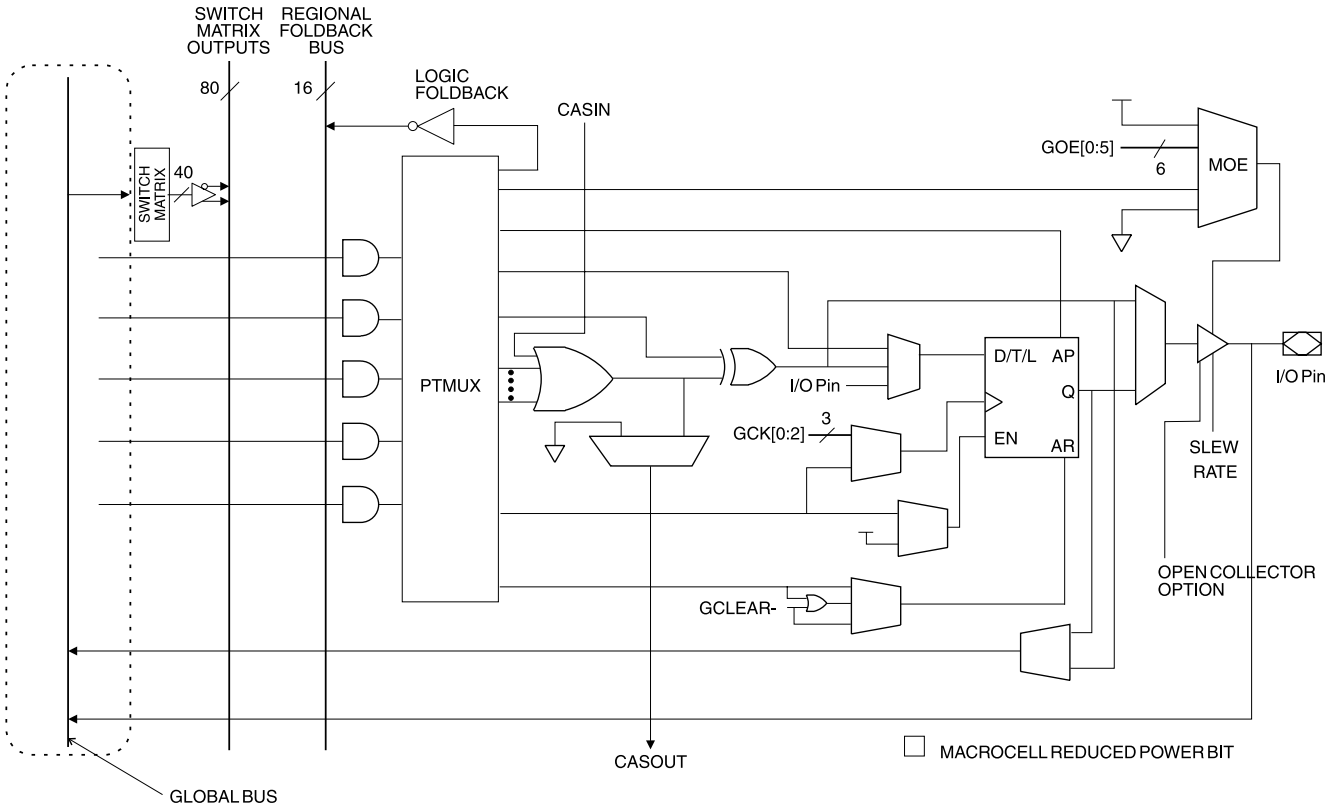
Each of the 32 macrocells generates a buried feedback that goes to the global bus. Each input and I/O pin also feeds into the global bus. The switch matrix in each logic block then selects 40 individual signals from the global bus. Each macrocell also generates a foldback logic term that goes to a regional bus. Cascade logic between macrocells in the ATF1502AS allows fast, efficient generation of complex logic functions. The ATF1502AS contains four such logic chains, each capable of creating sum term logic with a fan-in of up to 40 product terms.

The ATF1502AS macrocell, shown in Figure 1, is flexible enough to support highly complex logic functions operating at high speed. The macrocell consists of five sections: product terms and product term select multiplexer, OR/XOR/CASCADE logic, a flip-flop, output select and enable, and logic array inputs.

Unused product terms are automatically disabled by the compiler to decrease power consumption. A security fuse, when programmed, protects the contents of the ATF1502AS. Two bytes (16 bits) of User Signature are accessible to the user for purposes such as storing project name, part number, revision or date. The User Signature is accessible regardless of the state of the security fuse.

The ATF1502AS device is an in-system programmable (ISP) device. It uses the industry standard 4-pin JTAG interface (IEEE Std. 1149.1), and is fully compliant with JTAG's Boundary-scan Description Language (BSDL). ISP allows the device to be programmed without removing it from the printed circuit board. In addition to simplifying the manufacturing flow, ISP also allows design modifications to be made in the field via software.

Figure 1. ATF1502AS Macrocell



Product Terms and Select Mux

Each ATF1502AS macrocell has five product terms. Each product term receives as its inputs all signals from both the global bus and regional bus.

The product term select multiplexer (PTMUX) allocates the five product terms as needed to the macrocell logic gates and control signals. The PTMUX programming is determined by the design compiler, which selects the optimum macrocell configuration.

OR/XOR/ CASCADE Logic

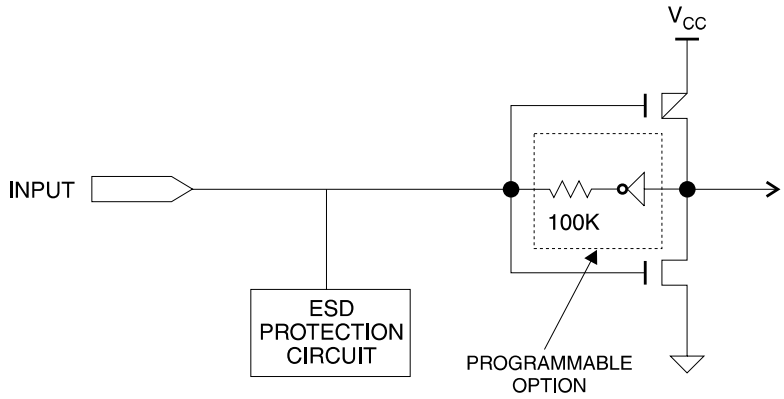
The ATF1502AS's logic structure is designed to efficiently support all types of logic. Within a single macrocell, all the product terms can be routed to the OR gate, creating a 5-input AND/OR sum term. With the addition of the CASIN from neighboring macrocells, this can be expanded to as many as 40 product terms with little additional delay.

The macrocell's XOR gate allows efficient implementation of compare and arithmetic functions. One input to the XOR comes from the OR sum term. The other XOR input can be a product term or a fixed high or low level. For combinatorial outputs, the fixed level input allows polarity selection. For registered functions, the fixed levels allow DeMorgan minimization of product terms. The XOR gate is also used to emulate T- and JK-type flip-flops.

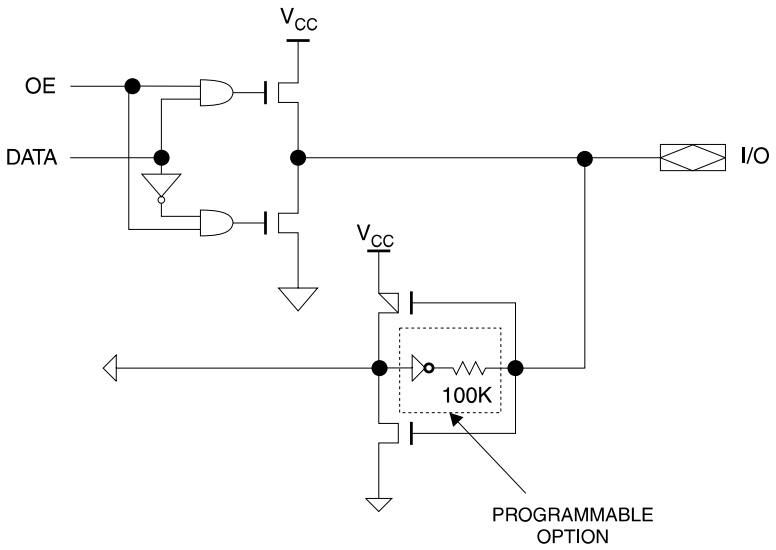
Flip-flop

The ATF1502AS's flip-flop has very flexible data and control functions. The data input can come from either the XOR gate, from a separate product term or directly from the I/O pin. Selecting the separate product term allows creation of a buried registered feedback within a combinatorial output macrocell. (This feature is automatically implemented by the fitter software). In addition to D, T, JK and SR operation, the flip-flop can also be configured as a flow-through latch. In this mode, data passes through when the clock is high and is latched when the clock is low.

Input Diagram



I/O Diagram



Speed/Power Management

The ATF1502AS has several built-in speed and power management features. The ATF1502AS contains circuitry that automatically puts the device into a low-power standby mode when no logic transitions are occurring. This not only reduces power consumption during inactive periods, but also provides proportional power savings for most applications running at system speeds below 50 MHz. This feature may be selected as a design option.

To further reduce power, each ATF1502AS macrocell has a reduced-power bit feature. This feature allows individual macrocells to be configured for maximum power savings. This feature may be selected as a design option.

The ATF1502AS also has an optional power-down mode. In this mode, current drops to below 10 mA. When the power-down option is selected, either PD1 or PD2 pins (or both) can be used to power down the part. The power-down option is selected in the design source file. When enabled, the device goes into power-down when either PD1 or PD2 is high. In the power-down mode, all internal logic signals are latched and held, as are any enabled outputs.

All pin transitions are ignored until the PD pin is brought low. When the power-down feature is enabled, the PD1 or PD2 pin cannot be used as a logic input or output. However, the pin's macrocell may still be used to generate buried foldback and cascade logic signals.

All power-down AC characteristic parameters are computed from external input or I/O pins, with reduced-power bit turned on. For macrocells in reduced-power mode (reduced-power bit turned on), the reduced-power adder, t_{RPA}, must be added to the AC parameters, which include the data paths t_{LAD}, t_{LAC}, t_{IC}, t_{ACL}, t_{ACH} and t_{SEXP}.

The ATF1502AS macrocell also has an option whereby the power can be reduced on a per-macrocell basis. By enabling this power-down option, macrocells that are not used in an application can be turned down, thereby reducing the overall power consumption of the device.

Each output also has individual slew rate control. This may be used to reduce system noise by slowing down outputs that do not need to operate at maximum speed. Outputs default to slow switching, and may be specified as fast switching in the design file.

Design Software Support

ATF1502AS designs are supported by several third-party tools. Automated fitters allow logic synthesis using a variety of high-level description languages and formats.

Power-up Reset

The ATF1502AS is designed with a power-up reset, a feature critical for state machine initialization. At a point delayed slightly from V_{CC} crossing V_{RST}, all registers will be initialized, and the state of each output will depend on the polarity of its buffer. However, due to the asynchronous nature of reset and uncertainty of how V_{CC} actually rises in the system, the following conditions are required:

1. The V_{CC} rise must be monotonic,
2. After reset occurs, all input and feedback setup times must be met before driving the clock pin high, and,
3. The clock must remain stable during T_D.

The ATF1502AS has two options for the hysteresis about the reset level, V_{RST}, Small and Large. During the fitting process users may configure the device with the Power-up Reset hysteresis set to Large or Small. Atmel POF2JED users may select the Large option by including the flag "-power_reset" on the command line after "filename.POF". To allow the registers to be properly reinitialized with the Large hysteresis option selected, the following condition is added:

4. If V_{CC} falls below 2.0V, it must shut off completely before the device is turned on again.

When the Large hysteresis option is active, I_{CC} is reduced by several hundred microamps as well.

Security Fuse Usage

A single fuse is provided to prevent unauthorized copying of the ATF1502AS fuse patterns. Once programmed, fuse verify is inhibited. However, the 16-bit User Signature remains accessible.

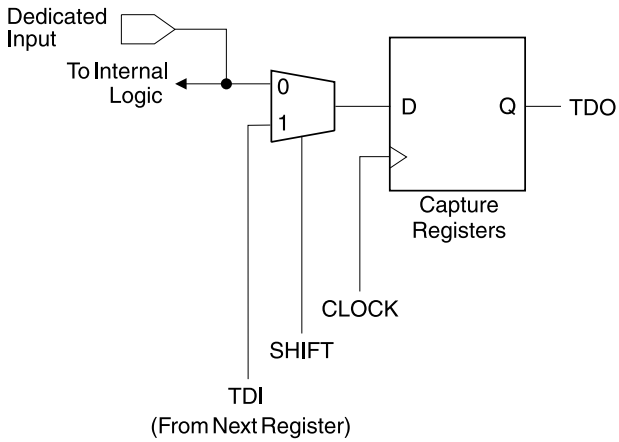
Programming

ATF1502AS devices are in-system programmable (ISP) devices utilizing the 4-pin JTAG protocol. This capability eliminates package handling normally required for programming and facilitates rapid design iterations and field changes.

JTAG Boundary-scan Cell (BSC) Testing

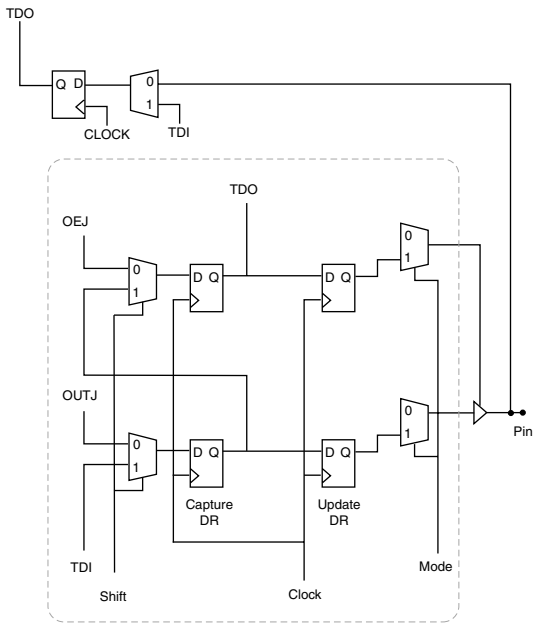
The ATF1502AS contains up to 32 I/O pins and four input pins, depending on the device type and package type selected. Each input pin and I/O pin has its own boundary-scan cell (BSC) in order to support boundary-scan testing as described in detail by IEEE Standard 1149.1. A typical BSC consists of three capture registers or scan registers and up to two update registers. There are two types of BSCs, one for input or I/O pin, and one for the macrocells. The BSCs in the device are chained together through the capture registers. Input to the capture register chain is fed in from the TDI pin while the output is directed to the TDO pin. Capture registers are used to capture active device data signals, to shift data in and out of the device and to load data into the update registers. Control signals are generated internally by the JTAG TAP controller. The BSC configuration for the input and I/O pins and macrocells is shown below.

BSC Configuration for Input and I/O Pins (Except JTAG TAP Pins)



Note: 1. The ATF1502AS has a pull-up option on TMS and TDI pins. This feature is selected as a design option.

BSC Configuration for Macrocell

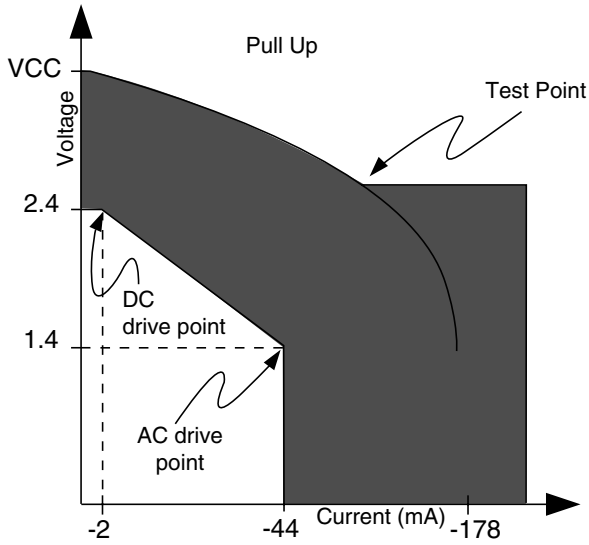


BSC for I/O Pins and Macrocells

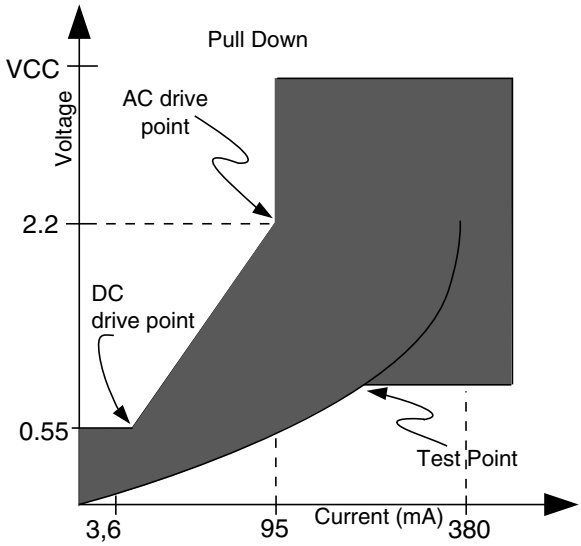
PCI Compliance

The ATF1502AS also supports the growing need in the industry to support the new Peripheral Component Interconnect (PCI) interface standard in PCI-based designs and specifications. The PCI interface calls for high current drivers, which are much larger than the traditional TTL drivers. In general, PLDs and FPGAs parallel outputs to support the high current load required by the PCI interface. The ATF1502AS allows this without contributing to system noise while delivering low output to output skew. Having a programmable high drive option is also possible without increasing output delay or pin capacitance. The PCI electrical characteristics appear on the next page.

PCI Voltage-to-current Curves for +5V Signaling in Pull-up Mode



PCI Voltage-to-current Curves for +5V Signaling in Pull-down Mode



PCI DC Characteristics (Preliminary)

Symbol	Parameter	Conditions	Min	Max	Units
V_{CC}	Supply Voltage		4.75	5.25	V
V_{IH}	Input High Voltage		2.0	V_{CC} + 0.5	V
V_{IL}	Input Low Voltage		-0.5	0.8	V
I_{IH}	Input High Leakage Current(1)	V_{IN} = 2.7V		70	µA
I_{IL}	Input Low Leakage Current(1)	V_{IN} = 0.5V		-70	µA
V_{OH}	Output High Voltage	I_{OUT} = -2 mA	2.4		V
V_{OL}	Output Low Voltage	I_{OUT} = 3 mA, 6 mA		0.55	V
C_{IN}	Input Pin Capacitance			10	pF
C_{CLK}	CLK Pin Capacitance			12	pF
C_{IDSEL}	IDSEL Pin Capacitance			8	pF
L_{PIN}	Pin Inductance			20	nH

Note: 1. Leakage current is with pin-keeper off.

PCI AC Characteristics (Preliminary)

Symbol	Parameter	Conditions	Min	Max	Units
$I_{OH(AC)}$	Switching Current High (Test High)	$0 < V_{OUT} \leq 1.4$	-44		mA
		$1.4 < V_{OUT} < 2.4$	-44 + (V_{OUT} - 1.4) /0.024		mA
		$3.1 < V_{OUT} < V_{CC}$		Equation A	mA
		V_{OUT} = 3.1V		-142	µA
$I_{OL(AC)}$	Switching Current Low (Test Point)	$V_{OUT} > 2.2V$	95		mA
		$2.2 > V_{OUT} > 0$	V_{OUT}/0.023		mA
		$0.1 > V_{OUT} > 0$		Equation B	mA
		V_{OUT} = 0.71		206	mA
I_{CL}	Low Clamp Current	$-5 < V_{IN} \leq -1$	-25 + (V_{IN} + 1) /0.015		mA
$SLEW_R$	Output Rise Slew Rate	0.4V to 2.4V load	1	5	V/ns
$SLEW_F$	Output Fall Slew Rate	2.4V to 0.4V load	1	5	V/ns

Notes: 1. Equation A: I_{OH} = 11.9 (V_{OUT} - 5.25) * (V_{OUT} + 2.45) for $V_{CC} > V_{OUT} > 3.1V$.
2. Equation B: I_{OL} = 78.5 * V_{OUT} * (4.4 - V_{OUT}) for $0V < V_{OUT} < 0.71V$.

DC and AC Operating Conditions

	Commercial	Industrial
Operating Temperature (Ambient)	0°C - 70°C	-40°C - 85°C
V_{CC} (5V) Power Supply	5V ± 5%	5V ± 10%

DC Characteristics

Symbol	Parameter	Condition			Min	Typ	Max	Units
I_{IL}	Input or I/O Low Leakage Current	$V_{IN} = V_{CC}$				-2	-10	µA
I_{IH}	Input or I/O High Leakage Current					2	10	
I_{OZ}	Tri-state Output Off-state Current	$V_O = V_{CC}$ or GND			-40		40	µA
I_{CC1}	Power Supply Current, Standby	V_{CC} = Max V_{IN} = 0, V_{CC}	Std Mode	Com.		60		mA
				Ind.		75		mA
			"L" Mode	Com.		10		µA
				Ind.		10		µA
I_{CC2}	Power Supply Current, Power-down Mode	V_{CC} = Max V_{IN} = 0, V_{CC}	"PD" Mode			1	5	mA
I_{CC3}[2]	Reduced-power Mode Supply Current, Standby	V_{CC} = Max V_{IN} = 0, V_{CC}	Std Mode	Com.		35		mA
				Ind.		40		mA
V_{IL}	Input Low Voltage				-0.3		0.8	V
V_{IH}	Input High Voltage				2.0		V_{CCIO} + 0.3	V
V_{OL}	Output Low Voltage (TTL)	$V_{IN} = V_{IH}$ or V_{IL} V_{CC} = MIN, I_{OL} = 12 mA		Com.	3.0		0.45	V
				Ind.			0.45	
	Output Low Voltage (CMOS)	$V_{IN} = V_{IH}$ or V_{IL} V_{CC} = MIN, I_{OL} = 0.1 mA		Com.			0.2	V
				Ind.			0.2	V
V_{OH}	Output High Voltage (TTL)	$V_{IN} = V_{IH}$ or V_{IL} V_{CC} = MIN, I_{OH} = -4.0 mA				2.4		V

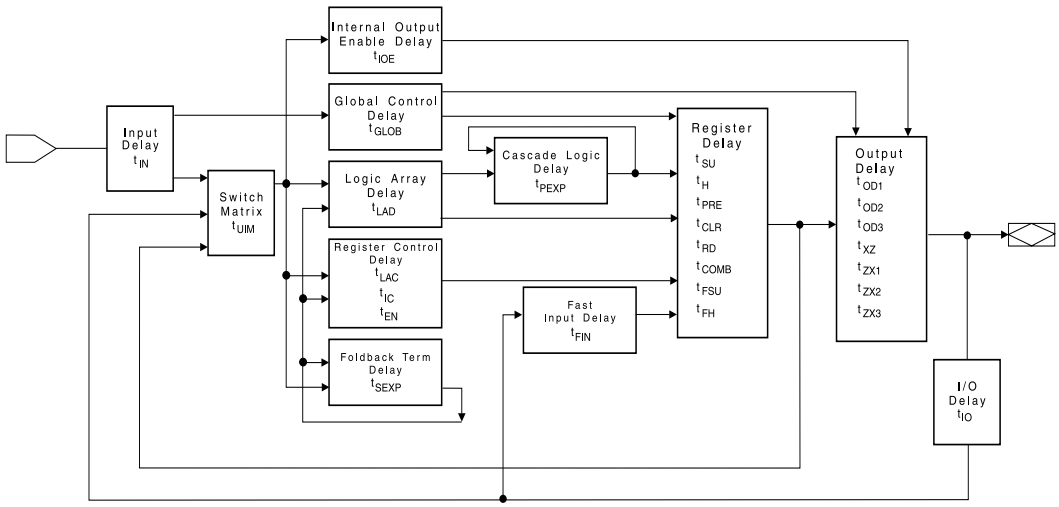
Notes: 1. Not more than one output at a time should be shorted. Duration of short circuit test should not exceed 30 sec.
2. I_{CC3} refers to the current in the reduced-power mode when macrocell reduced-power is turned on.

Pin Capacitance[1]

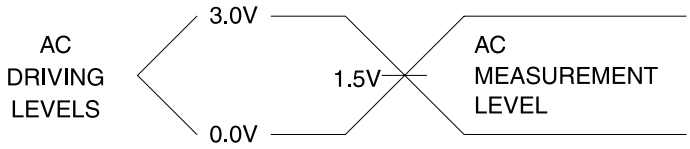
	Typ	Max	Units	Conditions
C_{IN}	8	10	pF	V_{IN} = 0V; f = 1.0 MHz
$C_{I/O}$	8	10	pF	V_{OUT} = 0V; f = 1.0 MHz

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.
The OGI pin (high-voltage pin during programming) has a maximum capacitance of 12 pF.

Timing Model

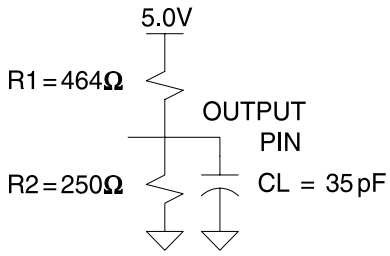


Input Test Waveforms and Measurement Levels



t_R, t_F = 1.5 ns typical

Output AC Test Loads



AC Characteristics (1)

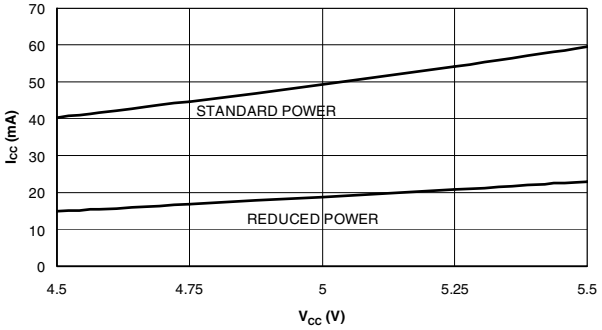
Symbol	Parameter	-7		-10		-15		-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input or Feedback to Non-registered Output		7.5		10	3	15		25	ns
t_{PD2}	I/O Input or Feedback to Non-registered Feedback		7		9	3	12		25	ns
t_{SU}	Global Clock Setup Time	6		7		11		20		ns
t_{H}	Global Clock Hold Time	0		0		0		0		ns
t_{FSU}	Global Clock Setup Time of Fast Input	3		3		3		5		ns
t_{FH}	Global Clock Hold Time of Fast Input	0.5		0.5		1		2		MHz
t_{COP}	Global Clock to Output Delay		4.5		5		8		13	ns
t_{CH}	Global Clock High Time	3		4		5		7		ns
t_{CL}	Global Clock Low Time	3		4		5		7		ns
t_{ASU}	Array Clock Setup Time	3		3		4		5		ns
t_{AH}	Array Clock Hold Time	2		3		4		6		ns
t_{ACOP}	Array Clock Output Delay		7.5		10		15		25	ns
t_{ACH}	Array Clock High Time	3		4		6		10		ns
t_{ACL}	Array Clock Low Time	3		4		6		10		ns
t_{CNT}	Minimum Clock Global Period		8		10		13		22	ns
f_{CNT}	Maximum Internal Global Clock Frequency	125		100		76.9		50		MHz
t_{ACNT}	Minimum Array Clock Period		8		10		13		22	ns
f_{ACNT}	Maximum Internal Array Clock Frequency	125		100		76.9		50		MHz
f_{MAX}	Maximum Clock Frequency	166.7		125		100		60		MHz
t_{IN}	Input Pad and Buffer Delay		0.5		0.5		2		2	ns
t_{IO}	I/O Input Pad and Buffer Delay		0.5		0.5		2		2	ns
t_{FIN}	Fast Input Delay		1		1		2		2	ns
t_{SEXP}	Foldback Term Delay		4		5		8		12	ns
t_{PEXP}	Cascade Logic Delay		0.8		0.8		1		2	ns
t_{LAD}	Logic Array Delay		3		5		6		8	ns
t_{LAC}	Logic Control Delay		3		5		6		8	ns
t_{IOE}	Internal Output Enable Delay		2		2		3		4	ns
t_{OD1}	Output Buffer and Pad Delay (Slow slew rate = OFF; V_{CC} = 5V; C_L = 35 pF)		2		1.5		4		6	ns
t_{ZX1}	Output Buffer Enable Delay (Slow slew rate = OFF; V_{CCIO} = 5.0V; C_L = 35 pF)		4.0		5.0		7		10	ns
t_{ZX2}	Output Buffer Enable Delay (Slow slew rate = OFF; V_{CCIO} = 3.3V; C_L = 35 pF)		4.5		5.5		7		10	ns

AC Characteristics (Continued)[1]

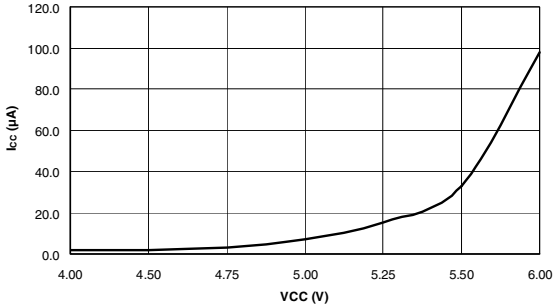
Symbol	Parameter	-7		-10		-15		-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{ZX3}	Output Buffer Enable Delay (Slow slew rate = ON; V_{CCIO} = 5.0V/3.3V; C_L = 35 pF)		9		9		10		12	ns
t_{XZ}	Output Buffer Disable Delay (C_L = 5 pF)		4		5		6		8	ns
t_{SU}	Register Setup Time	3		3		4		6		ns
t_H	Register Hold Time	2		3		4		6		ns
t_{FSU}	Register Setup Time of Fast Input	3		3		2		3		ns
t_{FH}	Register Hold Time of Fast Input	0.5		0.5		2		5		ns
t_{RD}	Register Delay		1		2		1		2	ns
t_{COMB}	Combinatorial Delay		1		2		1		2	ns
t_{IC}	Array Clock Delay		3		5		6		8	ns
t_{EN}	Register Enable Time		3		5		6		8	ns
t_{GLOB}	Global Control Delay		1		1		1		1	ns
t_{PRE}	Register Preset Time		2		3		4		6	ns
t_{CLR}	Register Clear Time		2		3		4		6	ns
t_{UIM}	Switch Matrix Delay		1		1		2		2	ns
t_{RPA}	Reduced-power Adder[2]		10		11		13		15	ns

Notes: 1. See ordering information for valid part numbers.
2. The t_{RPA} parameter must be added to the t_{LAD}, t_{LAC},t_{TIC}, t_{ACL}, and t_{SEXP} parameters for macrocells running in the reduced-power mode.

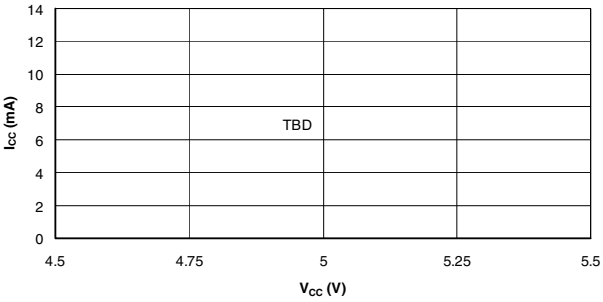
SUPPLY CURRENT VS. SUPPLY VOLTAGE
AS VERSION (T_A = 25°C, F = 0)



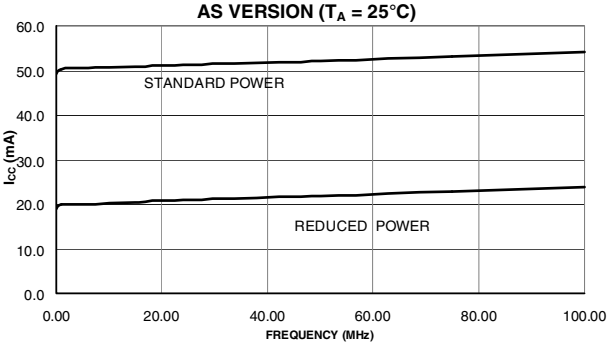
SUPPLY CURRENT VS. SUPPLY VOLTAGE
(T = 25°C, NON-TURBO, BIT6 = 0, BIT 30 = 0)



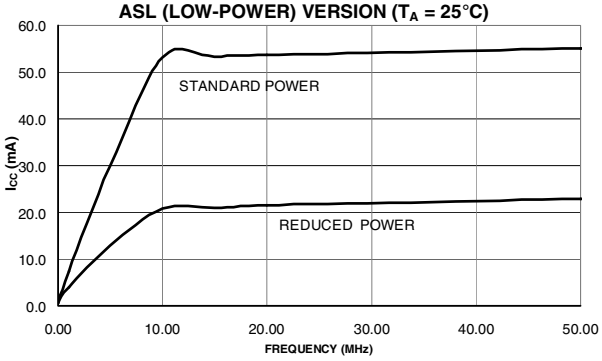
SUPPLY CURRENT VS. SUPPLY VOLTAGE
PIN-CONTROLLED POWER-DOWN MODE (T_A = 25°C, F = 0)



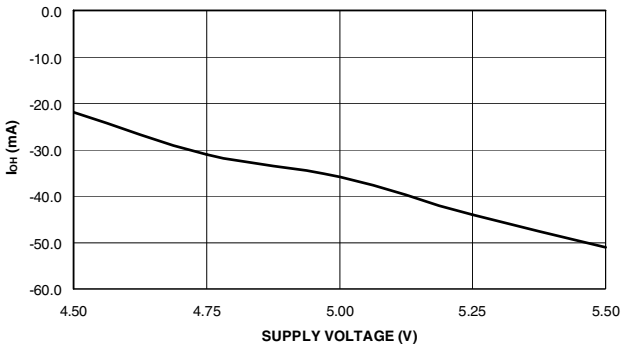
SUPPLY CURRENT VS. FREQUENCY
AS VERSION (T_A = 25°C)



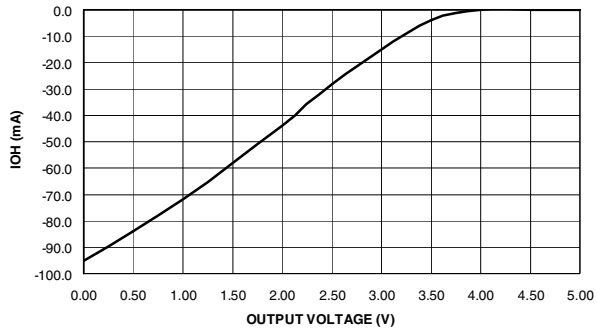
SUPPLY CURRENT VS. FREQUENCY
ASL (LOW-POWER) VERSION (T_A = 25°C)



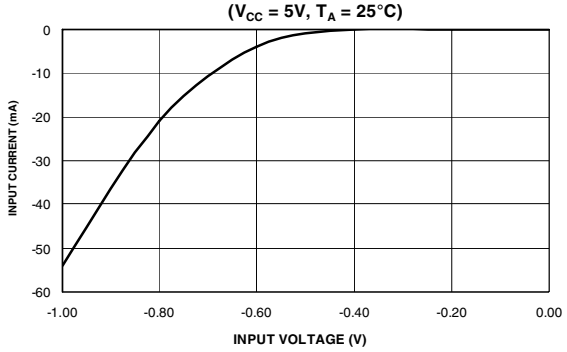
OUTPUT SOURCE CURRENT VS. SUPPLY VOLTAGE
(V_{OH} = 2.4V, T_A = 25°C)



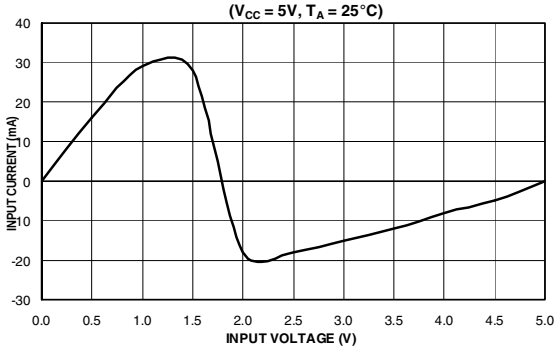
OUTPUT SOURCE CURRENT VS. OUTPUT VOLTAGE
(V_{CC} = 5V, T_A = 25°C)



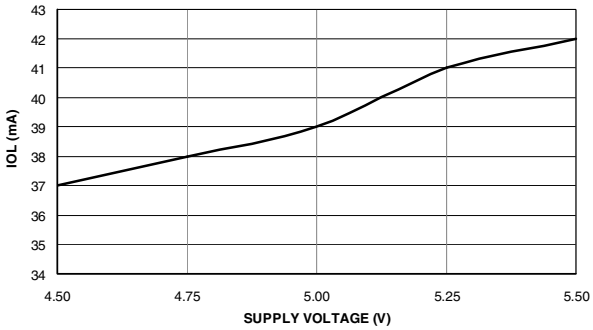
INPUT CLAMP CURRENT VS. INPUT VOLTAGE
(V_{CC} = 5V, T_A = 25°C)



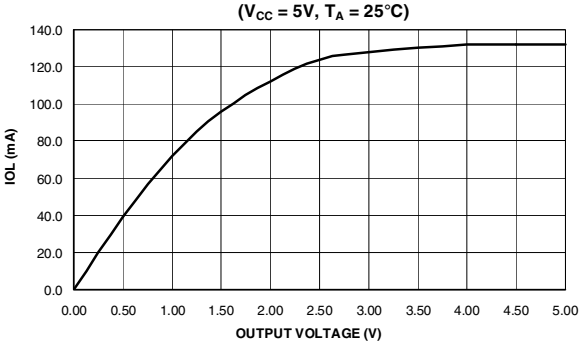
INPUT CURRENT VS. INPUT VOLTAGE
(V_{CC} = 5V, T_A = 25°C)



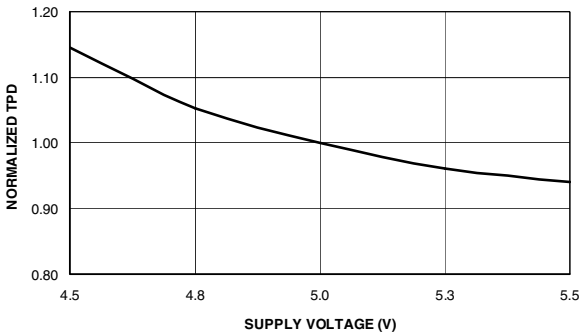
OUTPUT SINK CURRENT VS. SUPPLY VOLTAGE
(VOL = 0.5V, T_A = 25°C)



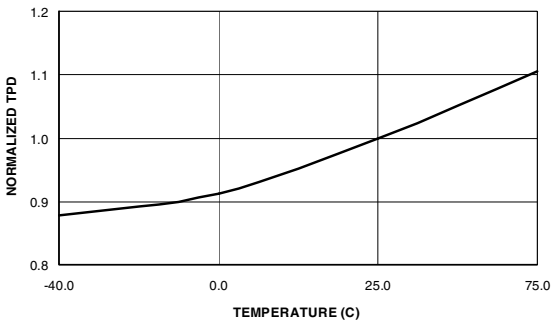
OUTPUT SINK CURRENT VS. OUTPUT VOLTAGE
(V_{CC} = 5V, T_A = 25°C)



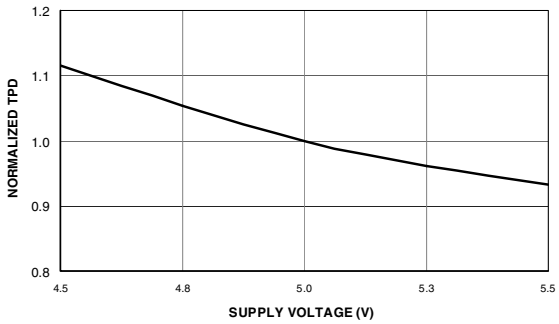
NORMALIZED TPD
VS. SUPPLY VOLTAGE (T_A = 25°C)



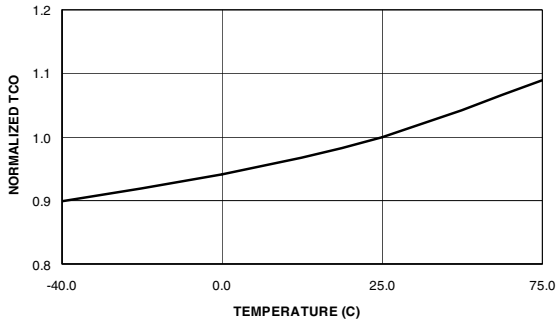
NORMALIZED TPD
VS. TEMPERATURE (V_{CC} = 5.0V)



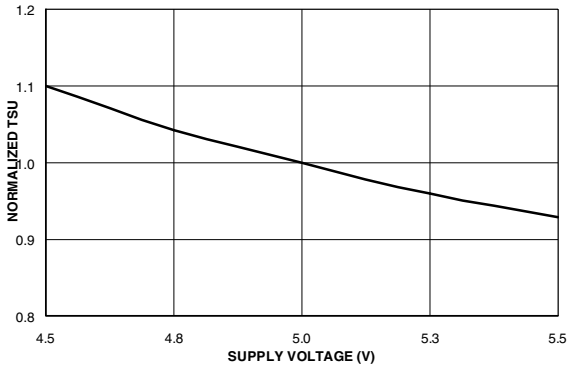
NORMALIZED TCO VS. SUPPLY VOLTAGE (T_A = 25°C)



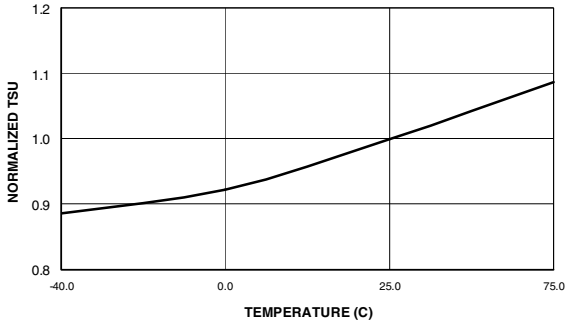
NORMALIZED TCO VS. TEMPERATURE (V_{CC} = 5.0V)



NORMALIZED TSU VS. SUPPLY VOLTAGE (T_A = 25°C)



NORMALIZED TSU VS. TEMPERATURE (V_{CC} = 5.0V)



ATF1502AS Dedicated Pinouts

Dedicated Pin	44-lead TQFP	44-lead J-lead
INPUT/OE2/GCLK2	40	2
INPUT/GCLR	39	1
INPUT/OE1	38	44
INPUT/GCLK1	37	43
I/O / GCLK3	35	41
I/O / PD (1,2)	5, 19	11, 25
I/O / TDI (JTAG)	1	7
I/O / TMS (JTAG)	7	13
I/O / TCK (JTAG)	26	32
I/O / TDO (JTAG)	32	38
GND	4, 16, 24, 36	10, 22, 30, 42
VCC	9, 17, 29, 41	3, 15, 23, 35
# of Signal Pins	36	36
# User I/O Pins	32	32

OE (1, 2)	Global OE pins
GCLR	Global Clear pin
GCLK (1, 2, 3)	Global Clock pins
PD (1, 2)	Power-down pins
TDI, TMS, TCK, TDO	JTAG pins used for boundary-scan testing or in-system programming
GND	Ground pins
VCC	VCC pins for the device (+5V)

ATF1502AS I/O Pinouts

MC	PLC	44-lead PLCC	44-lead TQFP
1	A	4	42
2	A	5	43
3	A/**PD1**	6	44
4/**TDI**	A	7	1
5	A	8	2
6	A	9	3
7	A	11	5
8	A	12	6
9/**TMS**	A	13	7
10	A	14	8
11	A	16	10
12	A	17	11
13	A	18	12
14	A	19	13
15	A	20	14
16	A	21	15
17	B	41	35
18	B	40	34
19	B	39	33
20/**TDO**	B	38	32
21	B	37	31
22	B	36	30
23	B	34	28
24	B	33	27
25/**TCK**	B	32	26
26	B	31	25
27	B	29	23
28	B	28	22
29	B	27	21
30	B	26	20
31	B	25	19
32	B	24	18

Ordering Information

t_{PD} (ns)	t_{CO1} (ns)	f_{MAX} (MHz)	Ordering Code	Package	Operation Range
7.5	4.5	166.7	ATF1502AS-7 AC44 ATF1502AS-7 JC44	44A 44J	Commercial (0°C to 70°C)
10	5	125	ATF1502AS-10 AC44 ATF1502AS-10 JC444	44A 44J	Commercial (0°C to 70°C)
			ATF1502AS-10 AI44 ATF1502AS-10 JI44	44A 44J	Industrial (-40°C to +85°C)
15	8	100	ATF1502AS-15 AC44 ATF1502AS-15 JC44	44A 44J	Commercial (0°C to 70°C)
			ATF1502AS-15 AI44 ATF1502AS-15 JI44	44A 44J	Industrial (-40°C to +85°C)
25	13	60	ATF1502ASL-25 AC44 ATF1502ASL-25 JC44	44A 44J	Commercial (0°C to 70°C)
			ATF1502ASL-25 AI44 ATF1502ASL-25 JI44	44A 44J	Industrial (-40°C to +85°C)

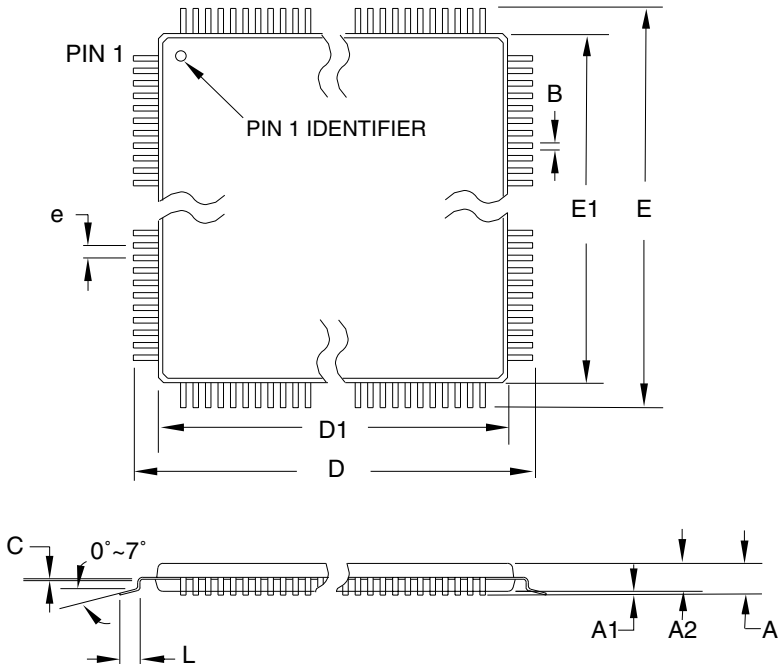
Using “C” Product for Industrial

To use commercial product for industrial temperature ranges, down-grade one speed grade from the “I” to the “C” device (7 ns “C” = 10 ns “I”) and de-rate power by 30%.

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier OTP (PLCC)

Packaging Information

44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

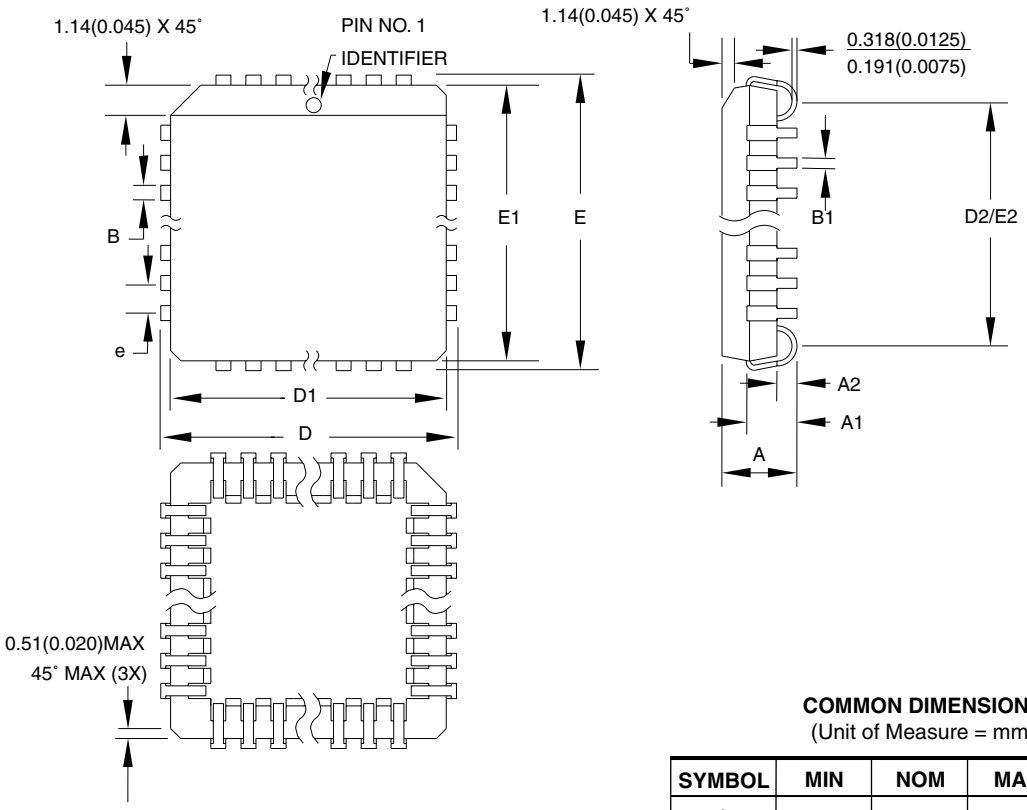
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44A,** 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B